



**CIRTEK ELECTRONICS CORPORATION**

116 East Avenue, Phase V, SEZ Laguna Technopark  
Binan, Laguna, Philippines

**PRODUCT INFORMATION**

Customer :

Device :

Die Size :

Package Type:

Device ID :

Water Material :

No. of Wires :

**MATERIAL INFORMATION**

Leadframe : A194 with spot Ag

Epoxy :

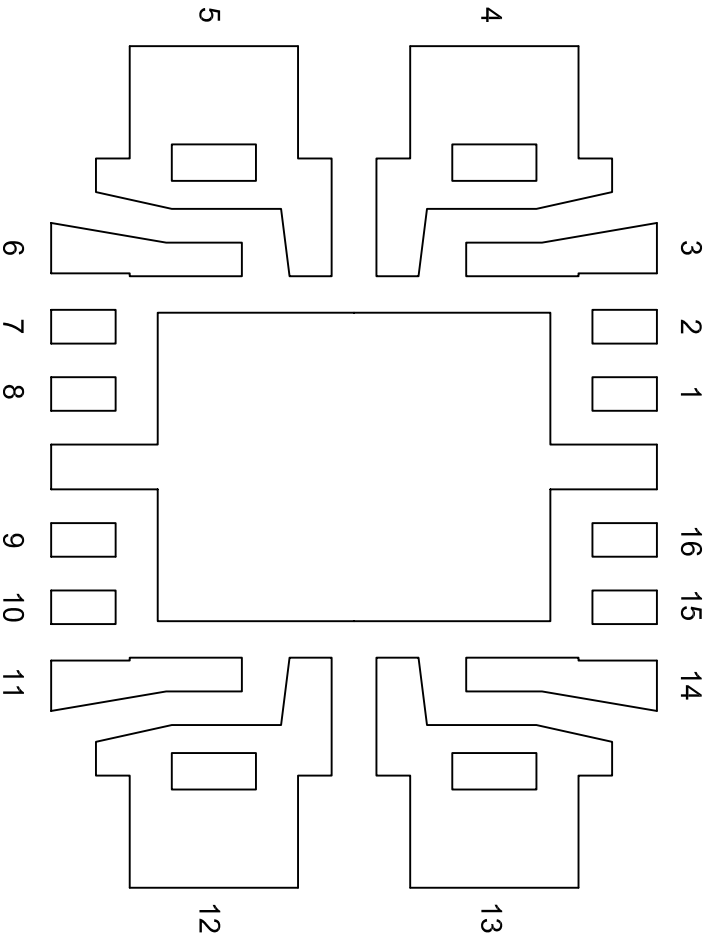
Molding Compound :

Pad Size : 110 X 140 mils

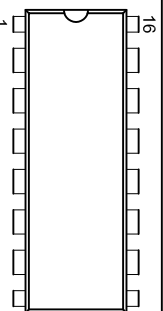
Wire size :

Lead Finish :

**MARKING INSTRUCTION**



BONDING DIAGRAM NO.



REF. BONDING DIAGRAM NO.

SCALE  
not to scale

DRAWN BY :

REVIEWED BY :

**REVISION NO.**

**APPROVALS**

Special instructions :

| REV. # | DESCRIPTION | PCN # | DEPT | APPROVALS | DATE |
|--------|-------------|-------|------|-----------|------|
|        |             |       | CUST |           |      |
|        |             |       | QSM  |           |      |
|        |             |       | QC   |           |      |
|        |             |       | MFG  |           |      |